

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Electronic components – Long-term storage of electronic semiconductor devices –
Part 8: Passive electronic devices**

**Composants électroniques – Stockage de longue durée des dispositifs
électroniques à semi-conducteurs –
Partie 8: Dispositifs électroniques passifs**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2020 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

Electropedia - www.electropedia.org

The world's leading online dictionary on electrotechnology, containing more than 22,000 terminological entries in English and French, with equivalent terms in 16 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - std.iec.ch/glossary

67,000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Recherche de publications IEC -

webstore.iec.ch/advsearchform

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: sales@iec.ch.

Electropedia - www.electropedia.org

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 000 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 16 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

Glossaire IEC - std.iec.ch/glossary

67 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Electronic components – Long-term storage of electronic semiconductor devices –
Part 8: Passive electronic devices**

**Composants électroniques – Stockage de longue durée des dispositifs électroniques à semiconducteurs –
Partie 8: Dispositifs électroniques passifs**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.020

ISBN 978-2-8322-8560-2

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 Storage considerations	9
4.1 Overview of passive components	9
4.2 Failure mechanisms	9
4.2.1 Occurrence of failure and driving force	9
4.2.2 Storage environment and mitigation for stimuli to prevent failure	11
4.3 Materials management.....	11
4.4 Storage media	12
4.5 Documentation/paper lot identifiers	12
4.6 Inventory check.....	12
4.7 Inventory dry packing refreshing	12
4.8 Inventory re-assessment.....	13
5 Baseline long-term storage requirements.....	13
5.1 General.....	13
5.2 Moisture sensitivity designation	13
5.3 Dry packing for storage	13
5.4 Non-moisture sensitive storage.....	13
5.4.1 General	13
5.4.2 Storage media	13
5.4.3 Lot data and labelling	13
5.5 Storage of moisture sensitive finished devices	14
5.5.1 Moisture barrier bag	14
5.5.2 Dunnage.....	14
5.5.3 Humidity indicator card	14
5.5.4 Desiccant	14
5.5.5 Labelling.....	14
5.5.6 Lot data and labelling	15
5.5.7 Storage environment	15
5.5.8 Process (temperature) sensitivity designation	15
Annex A (informative) Passive electronic device storage environment considerations	16
Bibliography.....	17
Table 1 – Failure mechanisms in storage and stimuli to mitigate during storage.....	10
Table 2 – Long-term environment – sustained condition requirements	11
Table 3 – Considerations for management, control and documentation during storage.....	12
Table A.1 – Long-term storage environment – sustained condition considerations	16

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE
OF ELECTRONIC SEMICONDUCTOR DEVICES –****Part 8: Passive electronic devices**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national (or) regional publication shall be clearly indicated in the latter.
<https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-4720c1e20220>
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62435-8 has been prepared by subcommittee IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

CDV	Report on voting
47/2595/CDV	47/2618/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62435 series, published under the general title *Electronic components – Long-term storage of electronic semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

iTeh STANDARD PREVIEW (standards.iteh.ai)

[IEC 62435-8:2020](#)

<https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020>

INTRODUCTION

This document applies to the long-term storage of passive electronic components.

This is a standard for long-term storage (LTS) of electronic devices drawing on the best long-term storage practices currently known. For the purposes of this document, LTS is defined as any device storage whose duration can be more than 12 months for product scheduled for long duration storage. While intended to address the storage of unpackaged semiconductors and packaged electronic devices, nothing in this document precludes the storage of other items under the storage levels defined herein.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions should be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence should often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, a priori, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations are recommended to be performed according to the state of the art.

The application of the approach proposed in this document in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

Some electronic device users have the need to store electronic devices for long periods of time. Lifetime buys are commonly made to support production runs of assemblies that will exceed the production timeframe of its individual parts. This puts the user in a situation requiring careful and adequate storage of such parts to maintain the as-received solderability and minimize any degradation effects to the part over time. Major degradation concerns are moisture, electrostatic fields, ultraviolet light, large variations in temperature, air-borne contaminants, and outgassing.

Warranties and sparring also present a challenge for the user or repair agency as some systems have been designated to be used for long periods of time, in some cases for up to 40 years or more. Some of the devices needed for repair of these systems will not be available from the original supplier for the lifetime of the system or the spare assembly may be built with the original production run but then require long-term storage. This document was developed to provide a standard for storing electronic devices for long periods of time. For storage

of devices that are moisture sensitive but that do not need to be stored for long periods of time, IEC TR 62258-3 can be consulted.

Long-term storage assumes that the device is going to be placed in uninterrupted storage for a number of years. It is essential that it is useable after storage. Particular attention should be paid to storage media surrounding the devices together with the local environment.

These guidelines do not imply any warranty of product or guarantee of operation beyond the storage time given by the manufacturer.

The IEC 62435 series is intended to ensure that adequate reliability is achieved for devices in user applications after long-term storage. Users are encouraged to request data from suppliers to applicable specifications to demonstrate a successful storage life as requested by the user. These standards are not intended to address built-in failure mechanisms that would take place regardless of storage conditions.

These standards are intended to give practical guide to methods of long-duration storage of electronic components where this is intentional or planned storage of product for a number of years. Storage regimes for work-in-progress production are managed according to company internal process requirements and are not detailed in this series of standards.

The overall standard is split into a number of parts. Parts 1 to 4 apply to any long-term storage and contain general requirements and guidance, whereas Parts 5 to 9 are specific to the type of product being stored. It is intended that the product specific part should be read alongside the general requirements of Parts 1 to 4.

Electronic components requiring different storage conditions are planned to be covered separately starting with Part 5.

[IEC 62435-8:2020](https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020)

The structure of the IEC 62435 series as currently conceived is as follows:

- Part 1 – General
- Part 2 – Deterioration mechanisms
- Part 3 – Data
- Part 4 – Storage
- Part 5 – Die and wafer devices
- Part 6 – Packaged or finished devices
- Part 7 – MEMS
- Part 8 – Passive electronic devices
- Part 9 – Special cases

ELECTRONIC COMPONENTS – LONG-TERM STORAGE OF ELECTRONIC SEMICONDUCTOR DEVICES –

Part 8: Passive electronic devices

1 Scope

This part of the IEC 62435 series on long-term storage is applied to passive electronic devices in long-term storage that can be used as part of obsolescence mitigation strategy. Long-term storage refers to a duration that can be more than 12 months for product scheduled for storage. Storage typically begins when components are packed at the originating supplier where the pack date or date code are assigned to the product. It is the responsibility of the distributor and the customer to control and manage the aging inventory upon receipt of the dated product. Alternatively, a supplier-customer agreement can be established to manage the aging inventory. Philosophy, good working practice, and general means to facilitate the successful long-term storage of electronic components are also addressed.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60749-20, *Semiconductor devices – Mechanical and climatic test methods – Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat*

IEC 60749-20-1, *Semiconductor devices – Mechanical and climatic test methods – Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat*

IEC 61760-4, *Surface mounting technology – Part 4: Classification, packaging, labelling and handling of moisture sensitive devices*

JEDEC J-STD-075, *Classification of non-IC electronic components for assembly processes*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

passive, adj

<electronic component> qualifies a circuit element or a circuit for which the time integral of the instantaneous power cannot be negative over any time interval beginning at an instant before the first supply of electric energy

EXAMPLE Resistor, inductor, capacitor, fuse, magnetic switch, crystal oscillator, diode, led

Note 1 to entry: Under periodic conditions, the integration interval can comprise an integral number of periods instead of beginning at minus infinity.

Note 2 to entry: A passive circuit normally does not contain voltage or current sources.

[SOURCE: IEC 60050-131:2002, 131-11-34, modified – A domain has been specified at the beginning of the definition and some examples have been added.]

3.2 storage environment

specially controlled storage area, with particular control of temperature, humidity, atmosphere and any other conditions depending on the product requirements

[SOURCE: IEC 62435-1:2017, 3.1.1]

3.3 critical moisture limit

maximum safe equilibrium moisture content for a specific encapsulated device at reflow assembly or rework

3.4 long-term storage

LTS

planned storage of components to extend the life-cycle for a duration with the intention of supporting future use

Note 1 to entry: Allowable storage durations will vary by form factor (e.g., packing materials, shape) and storage conditions. In general, long-term storage is longer than 12 months.

[SOURCE: IEC 62435-1:2017, 3.1.2]

[IEC 62435-8:2020](#)

<https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020>

3.5 LTS storeroom

area containing components that have additional packaging for storage to protect from moisture or from mechanical impact or for ease of identification or handling

3.6 moisture-sensitive device

MSD

device that has moisture absorption or moisture retention and whose quality or reliability is affected by moisture

3.7 electronic device

packaged electrical, electronic, electro-mechanical (EEE) item, or assemblies using such items

[SOURCE: IEC 62435-1:2017, 3.1.3]

3.8 desiccant

hygroscopic substance used to remove moisture from an atmosphere

3.9 moisture barrier bag

MBB

storage bag manufactured with a flexible laminated vapour barrier film that restricts the transmission of water vapour

Note 1 to entry: Refer to IEC 60749-20-1 for packaging of moisture sensitive products.

[SOURCE: IEC 62435-1:2017, 3.1.4]

3.10

humidity indicator card

HIC

card printed with a moisture sensitive chemical that changes from blue to pink in the presence of water vapour

[SOURCE: IEC 62435-1:2017, 3.1.5, modified – The bracketed information "(cobalt bromide)" has been removed from the definition.]

3.11

water vapour transmission rate

WVTR

measure of permeability of MBBs to water vapour

3.12

dunnage

all the matter stored in a moisture barrier bag that is additional to the packaged electronic component

3.13

electro-static discharge

ESD

transfer of electric charge between bodies of different electrostatic potentials in proximity or through direct contact

[SOURCE: IEC 60050-561:2014, 561-03-06]

[IEC 62435-8:2020](https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020)

[https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-](https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020)

4 Storage considerations [cbc4120de943/iec-62435-8-2020](https://standards.iteh.ai/catalog/standards/sist/59a5a32b-4795-4a5f-b401-cbc4120de943/iec-62435-8-2020)

4.1 Overview of passive components

Passive components are not able to control current where the instantaneous power cannot be negative therefore there is no power gain before the application of electric energy. Common examples of passives are resistors, capacitors, inductors, transformers and diodes of all types. Often electromechanical relays, quartz crystals and fuses are also to be considered passive components for the purpose of long-term storage requirements. Passive components are made using a wide range of technologies, materials and manufacturing processes.

Passive components are surface mounted to electronic packages, modules and boards as either discrete components or packaged components that vary in size, typically larger than 1 mm in the smallest dimension. Passive miniaturization has led to packaged passives. Passives are also integrated or embedded into other packaged components, modules and boards.

Passive components can experience many of the same failure modes as other components and the storage program should consider the end use and failure mechanisms related to the function of the component. An example list below may be used as a basis for consideration in storage related risk assessments.

4.2 Failure mechanisms

4.2.1 Occurrence of failure and driving force

Failures during long-term storage should be mitigated by control of the stimuli driving given failure modes of interest as defined by a failure modes and effects analysis (FMEA). Storage related failures are often detected as modes of non-operation, visual quality or other non-conformance. The modes of failure during storage are typically related to a failure mechanism

that is driven by a physical stimuli or condition. Successful long-term storage is accomplished by controlling the failure mechanism stimuli as identified using a failure modes and effect analysis based on information from technology development and testing. Example failure stimuli are given in Table 1. Additional examples of deterioration mechanisms are found in IEC 62435-2. Successful long-term storage is accomplished by mitigating failures through control of the stimuli or driving force.

Table 1 – Failure mechanisms in storage and stimuli to mitigate during storage.

Failure mechanism	Failure mechanism detail	Failure mode	Mechanism stimuli
Popcorn effect	High rate vapour expansion within a passive during surface mounting	Open circuit, blistering, component cracks or parametric electrical degradation	Temperature increase leading to moisture vapour
Handling damage	Cracking	Open, short, visible crack	Application of force
	Visible scratch/smudge	Open, short, surface mark	Mechanical abrasion
Staining residue	Change in surface appearance and specification resulting from unplanned exposure to oxidizing contents	Visible defect, non-conforming appearance and potential of misprocessing	Exposure resulting in aging, oxidation or hardening of residue
Polymer material aging	Polymer embrittlement	Visible cracking, open or shorting or parametric degradation	Temperature exposure, residual mechanical stress and bright light
Storage media issues	Tape on reel or tube embrittlement/aging	Misalignment during processing	Temperature exposure, mechanical stressing and bright light
	Tube aging embrittlement	Dropped parts from broken tray media or parts out of formed pocket	Temperature, handling and bright light
	Box aging embrittlement	Dropped parts Foreign material	Temperature and bright light
	ESD coating degradations	Opens, shorts or parametric degradation from ESD	Triboelectric charging or charge potential difference
	Label aging	Illegible mark	Bright light, temperature
		Missing label	Temperature and bright light
Brittle flaking – partial label	Temperature and bright light		
Indirect material issues	Moisture barrier bag leak	Humidity indicator card trigger, visual non-conformance	Handling abrasion, bending and shock events
	Humidity Indicator Card activated	Incorrect colour or no moisture exposure indicated	Temperature, humidity Exposure before use
	Label aging	Illegible mark	Bright light, temperature
		Missing label	Temperature and bright light
Brittle flaking – partial label	Temperature and bright light		
Solderability	Inability to form a good solder joint	Post surface mount electrical open or parametric shift	Temperature, humidity Exposure
Corrosion	Electro-chemical reaction leading failure or reduced mechanical functionality	Open, short, visual non-conformance related sense signal degradation or failure	Temperature, galvanic cell, chemical residue
Wear	Degradation of functionality related to use of a mechanical function	Sense signal degradation	Mechanical cycling, dynamic stresses-vibration
Foreign material	Unexpected particle or other material that prevents mechanical functionality	Sense signal degradation	Mechanical cycling, dynamic stresses-vibration
Tin whiskers	Whisker filament formed by dislocations in metal films with a gradient in surface mechanical stress	Visual whiskers, short	Bright Sn surface finish (un-alloyed) crystal dislocation growth (in un-mitigated parts) Sulphur gas catalysed reaction